●USP-6B07 Power Dissipation

Power dissipation data for the USP-6B07 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition: Mount on a board

Ambient: Natural convection

Soldering: Lead (Pb) free

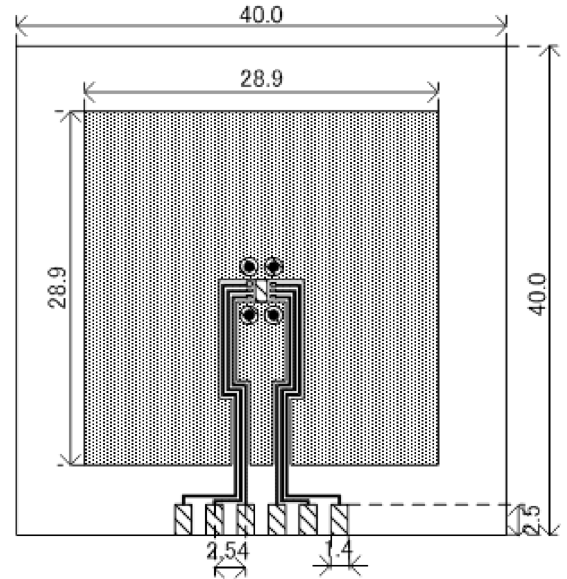
Board Dimensions: 40 x 40 mm (1600mm^2 in one side)

Copper (Cu) traces occupy 50% of the board area In top and back faces Package heat-sink is tied to the copper traces

Material: Glass Epoxy (FR-4)

Thickness: 1.6 mm

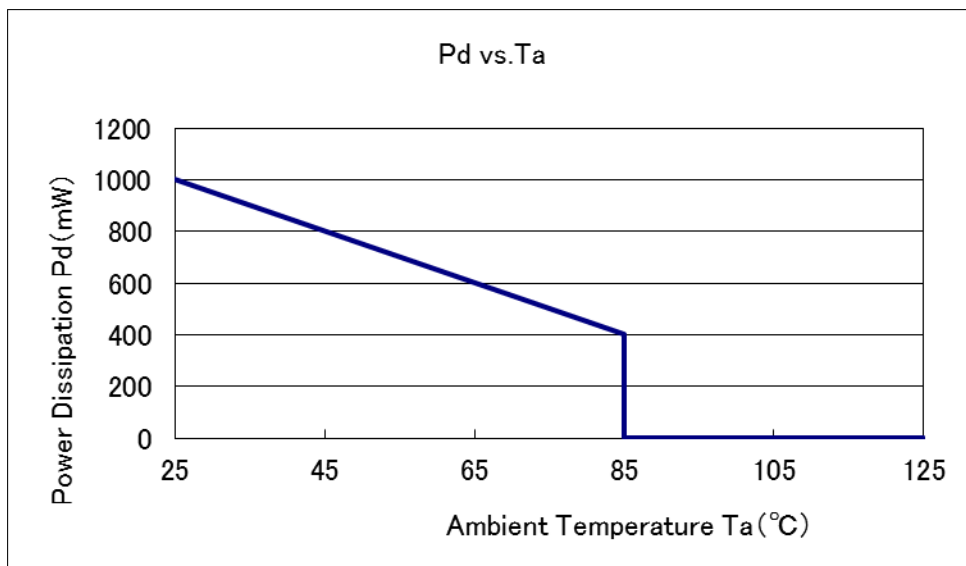
Through-hole: 4 x 0.8 Diameter



Evaluation Board (Unit:mm)

2. Power Dissipation vs. Ambient Temperature

Ambient Temperature (℃)	Power Dissipation Pd (mW)	Thermal Resistance (℃/W)
25	1000	100.00
85	400	



●USP-6B07(DAF) Power Dissipation

Power dissipation data for the USP-6B07(DAF) is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition: Mount on a board

Ambient: Natural convection

Soldering: Lead (Pb) free

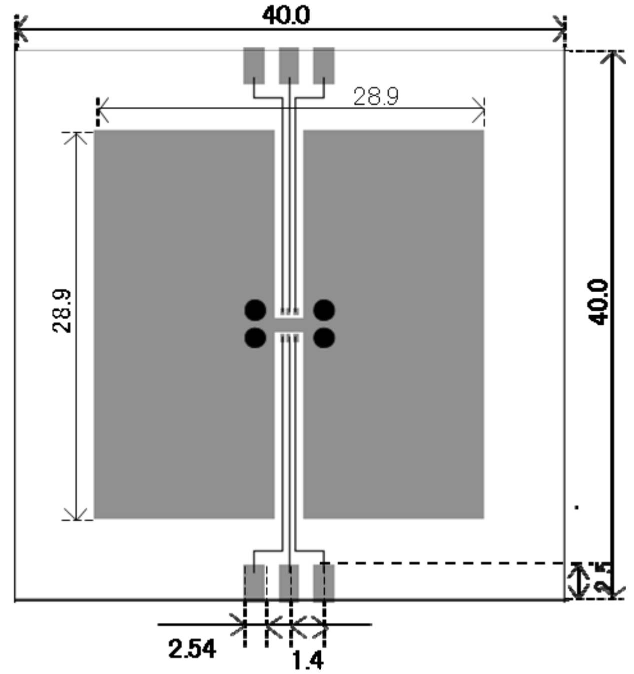
Board Dimensions: 40 x 40 mm (1600mm^2 in one side)

Copper (Cu) traces occupy 50% of the board area In top and back faces Package heat-sink is tied to the copper traces

Material: Glass Epoxy (FR-4)

Thickness: 1.6 mm

Through-hole: 4 x 0.8 Diameter



Evaluation Board (Unit:mm)

2. Power Dissipation vs. Ambient Temperature

Ambient Temperature (℃)	Power Dissipation Pd (mW)	Thermal Resistance (℃/W)
25	750	133.33
85	300